

Application No.: 10/387,203

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application.

**IN THE CLAIMS:**

1. (Original) A method for forming an out-of-plane coil structure, comprising: depositing a layer of an elastic material on a substrate, the elastic material having an intrinsic stress profile;

photolithographically patterning the layer of elastic material into an elastic member; and under-cut etching a portion of the substrate under the elastic member to release a free portion of the elastic member from the substrate, an anchor portion of the elastic member remaining fixed to the substrate;

wherein the intrinsic stress profile in the elastic member biases the free portion of the coil structure away from the substrate, forming a loop winding and causing a free end to contact a point on the substrate; and

connecting the free end to the substrate.

2. (Original) The method of claim 1, wherein the free end contacts a point on the substrate other than its release point.

3. (Canceled).

4. (Original) The method of claim 1, wherein the elastic member is formed of an electrically conductive material.

5. (Currently Amended) The method of claim 1, further comprising: ~~after photolithographically patterning the layer of elastic material into an elastic member, prior to under-cut etching the portion of the substrate under the elastic member, forming a mechanical stop at a point on the substrate for positioning return of the free end.~~